



News Release

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Silicon Genesis Displays Latest Layer Transfer Technology at SEMICON West 2007

Layer Transfer equipment and process technology for SOI, SOQ, SOG, DSB

SAN JOSE, CA, July 17, 2007 – Silicon Genesis, a leader in process and technology for engineered substrates announced today that it will be displaying its latest technology for the semi, optoelectronic and display markets at SEMICON West July 17-19 at the Moscone Center in San Francisco (Booth #8253 - West Hall Level 2).

As next generation semiconductor devices begin to take shape, the requirements for heat dissipation, power consumption and device mobility are more important than ever. One method to achieve better performance is through engineered substrate solutions. Silicon-on-Insulator (SOI) and Direct Silicon Bond (DSB) are helping to achieve these challenging, new requirements.

For the display and optoelectronic markets Silicon-on-Quartz (SOQ), Silicon-on-Glass (SOG), and Germanium-on-Insulator (GeOI) technologies are opening new avenues to high performance devices. For the LED and Laser Diode markets where cost has limited commercial availability and growth, GaN and SiC engineered substrates, fabricated using layer transfer techniques, enable simpler manufacturing flows and substantial cost reduction.

“SiGen has spent the last nine years developing the technology, processes, know-how and equipment for these growth markets. We are now seeing the fruits of our labors as more customers implement engineered substrates for high performance devices.” said Francois Henley, President and CEO of Silicon Genesis.

SiGen is also developing layer transfer technology for the fast-growing solar market. The techniques and experiences learned from engineering substrate solutions for the semiconductor industry has given SiGen a unique and deep understanding to apply this technology to lower solar cell cost and increase efficiency.

Silicon Genesis Corporation (SiGen) develops and licenses engineered substrate technology for solar, semiconductor, optoelectronics and display markets. Headquartered in San Jose, California (Silicon Valley), the Company's proprietary NanoCleave™ (Layer-transfer), NanoBond™ (Plasma-activated bonding), and NanoSmooth™ (Epi Smoothing/Epi Thickening) process steps have allowed SiGen to become a leading provider of innovative-engineered substrates through its process and technology licensing. SiGen promotes its layer-transfer (LT) and engineered substrate technologies by continued development of its advanced process and equipment technologies as well as through strategic alliances. SiGen's processes and technology enable its customers to develop new applications with greater functionality and higher speed, while improving cost, power efficiency, and heat dissipation. For more information on SiGen, please visit us at www.sigen.com